

Remarks

Favorable review is requested in view of the following remarks. Claims 23 – 31 and 37 – 42, which were presented in the Response to Restriction Requirement that was filed on January 10, 2005, are pending in the application.

The response presented herein is in reply to the Examiner's belief that the Applicants' Response to Restriction Requirement that was filed on January 10, 2005 is not fully responsive to the Office Action mailed April 7, 2004.

The following rejections were presented in the Office Action mailed April 7, 2004. Applicants believe the following remarks are in compliance with 37 C.F.R. § 1.111.

Claim Rejections under 35 U.S.C. §§ 102 and 103

Claims 1 – 2, 4 – 5, 13 – 15, and 18 – 19 were rejected under 35 U.S.C. § 102(b) as being anticipated by Ainslie et al. (U.S. Patent No. 4,761,699). Claims 7 – 12, 16, and 20 – 22 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Ainslie et al. Applicants respectfully traverse these rejections, and respectfully request reconsideration in view of the following comments.

In view of the rejections presented, the following comments are provided. Claim 37 requires a bond pad for electrically connecting the device to a holding member, the bond pad having at least two layers. Ainslie et al. do not disclose or suggest a bond pad having at least two layers.

In contrast, Ainslie et al. disclose a lead termination 41 and contact pads 70. They are two distinct items. Contact pads 70 provide mechanical connection to the suspension 40, not an electrical connection. See Figures 4 – 7 of Ainslie et al. Ainslie et al. disclose that the contact pads 70 can include a corrosion-resistant film 78. However, Ainslie et al. do not disclose or suggest any such film for lead termination 41. In fact, lead termination 41 is not considered a pad, but a lead termination. Therefore, there is no disclosure or suggestion for adding the corrosion-resistant film 78 described for the contact pads 70 to the lead termination 41. The distinction made by Ainslie et al. regarding the contact pads 70 and lead termination 41 cannot now be removed for the convenience of an obvious rejection. Consequently, Ainslie et al. do not disclose or suggest a bond pad having at least two layers.

Conclusion

In view of the comments presented herein, favorable reconsideration in the form of a Notice of Allowance is respectfully requested. If any further questions should arise, the Examiner is invited to contact Applicants' representative at the number listed below.

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CERTIFICATION UNDER 37 C.F.R. § 1.8

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I hereby certify that this Response is being transmitted via facsimile to facsimile number 703-872-9306 at the United States Patent and Trademark Office Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date shown above.

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